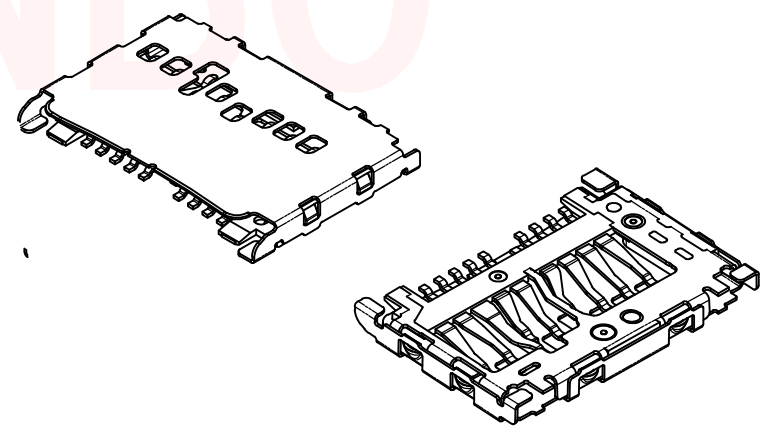
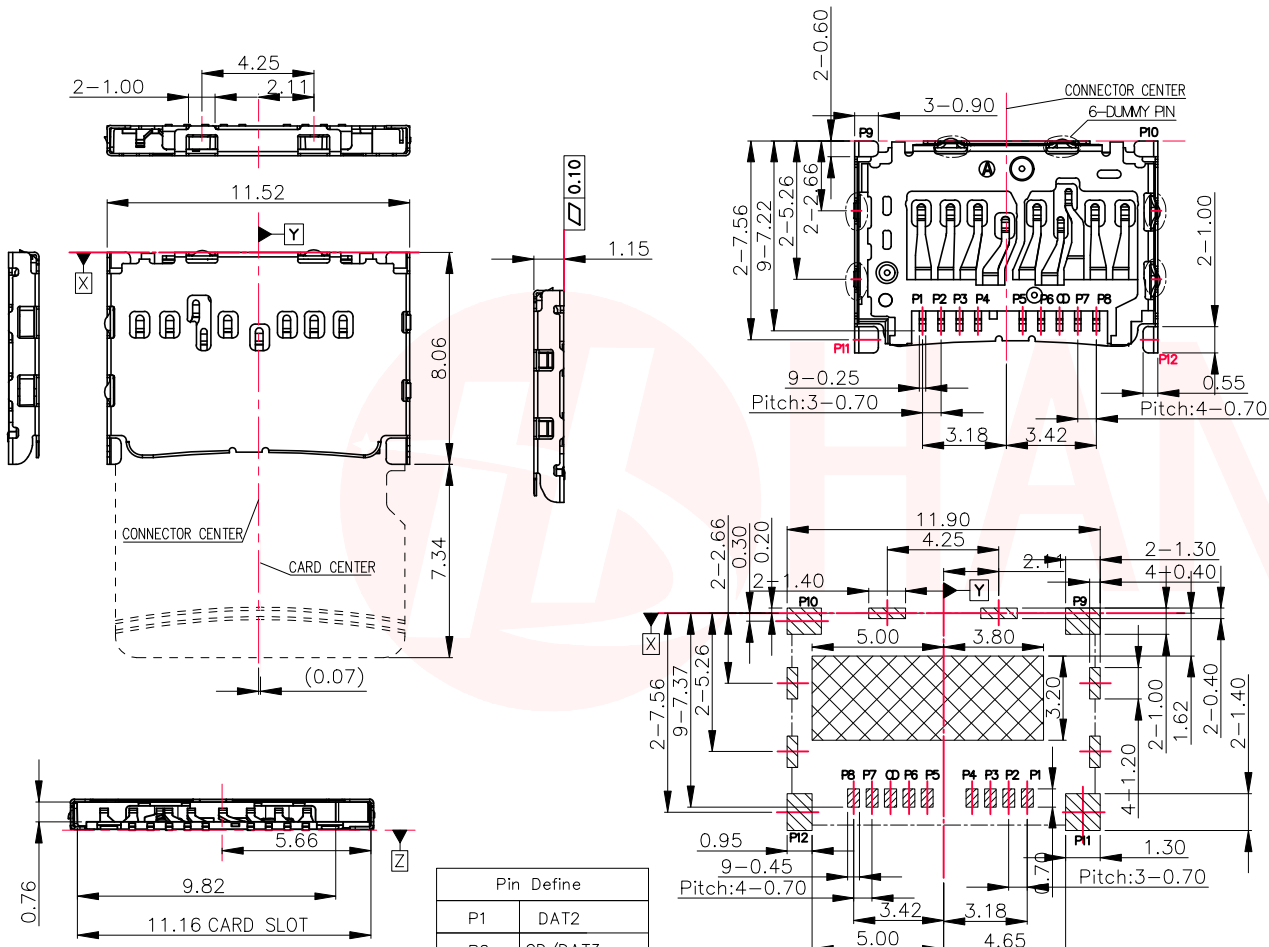




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

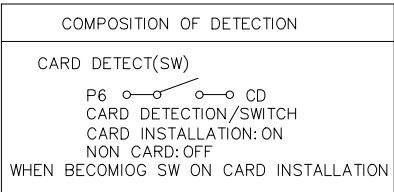
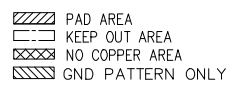


NOTE:

- Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP MG350) Color Black UL 94V-0.
 - 1-2 Contact: Phosphor Bronze (C5210R-SH T=0.12mm)
 - 1-3 Cover: SUS304-H T=0.10mm
- Plating:
 - 2-1 Contact terminal: Contact area: Gold 2u" Min. Middle Pd-Ni 8u" min. Solder area: Gold 1u" Min. Underplating: Ni overall 80U" Min.
 - 2-2 Cover: Underplating: Ni overall 30U" Min. Solder area: Gold 1u" Min.
- Specification:
 - 3-1. Contact Current Rating: 0.5 Amperes.
 - 3-2. Dielectric Withstanding Voltage: AC500V r.m.s.
 - 3-3. Insulation Resistance: 1000 Megohms Minimum At DC 500V.
 - 3-4. Contact Resistance: 100 mΩ Maximum.
 - 3-5. Mating Cycles: 5,000 Cycles.
 - 3-6. Operating Temperature: -25°C~+60°C.
- Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
- Part Must Comply Taisol HF WD-3-1-091 Specification.
- Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
CD	CARD DETECT
P7	DAT0
P8	DAT1
P9-P12	GND

RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD		
DECIMALS:	ANGLES:	TITLE	MICRO SD H1.15 CARD CONN	
X : ±0.30	X : ±2°	DWN	xiiong	PART NO. MR-1205
X.X : ±0.20	X.X : ±1°	CHKD	lee	SCALE: 1:1 UNIT: mm
X.XX : ±0.10		APVD	wang	SIZE: A4 SHEET: 10F 1 REV: A4
CUSTOMER COPY				